

□ MN101C45 Series

Type	MN101C457	MN101CP427
Internal ROM type	Mask ROM	EPROM
ROM (byte)	16K	
RAM (byte)	0.5K	
Package (Lead-free)	QFP044-P-1010F	
Minimum Instruction Execution Time	0.10 μ s (at 4.5 V to 5.5 V, 20 MHz) 0.238 μ s (at 2.7 V to 5.5 V, 8.39 MHz) 0.477 μ s (at 2.0 V to 5.5 V, 4.19 MHz)	0.10 μ s (at 4.5 V to 5.5 V, 20 MHz) 0.238 μ s (at 2.7 V to 5.5 V, 8.39 MHz)

■ Interrupts

RESET. Watchdog. External 0 to 2. Timer 2 to 5. Time base. Serial 0. A/D conversion finish

■ Timer Counter

8-bit timer \times 2

Timer 2Square-wave/8-bit PWM output. Event count. Synchronous output event

Timer 3Square-wave output. Event count. Remote control carrier output. Serial 0 baud rate timer

Timer 2, 3 can be cascade-connected

16-bit timer \times 1

Timer 4Square-wave/16-bit PWM output. Event count. Synchronous output event. Input capture

Time base timer: One-minute count setting. Independently operable 8-bit timer 5

Watchdog timer \times 1

■ Serial interface

Synchronous type/Simple UART (half-duplex) \times 1: Serial 0

■ I/O Pins

I/O 26 : Common use. 16. Specified pull-up resistor available. Input/output selectable (bit unit): 26

Input 11 : Common use. Specified pull-up resistor available

■ A/D converter

10-bit \times 8 channels (with S/H)

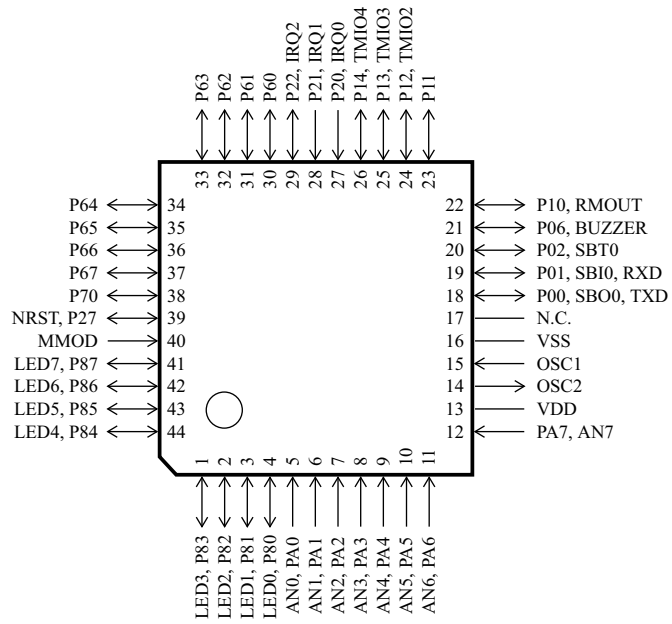
■ Special Ports

Buzzer output. Remote control carrier output. High-current drive port

■ Electrical Characteristics (Supply current)

Parameter	Symbol	Condition	Limit			Unit
			min	typ	max	
Operating supply current	IDD1	fosc = 20 MHz. VDD = 5 V		15	40	mA
	IDD2	fosc = 8.39 MHz. VDD = 5 V		6	18	mA
Supply current at STOP	IDD3	VDD = 5 V. Ta = 25 °C			2	μ A
	IDD4	VDD = 5 V. Ta = -40 °C to +85 °C			20	μ A

■ Pin Assignment
QFP044-P-1010F



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